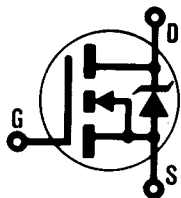


IRFV460



N-CHANNEL

They are well suited for applications such as switching power supplies and virtually any application where military and/or high reliability is required.

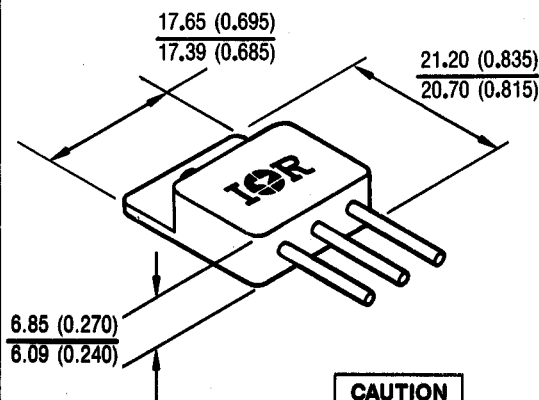
Product Summary

Part Number	V_{DSS}	$R_{DS(on)}$	I_D
IRFV460	500V	0.27 Ω	21A

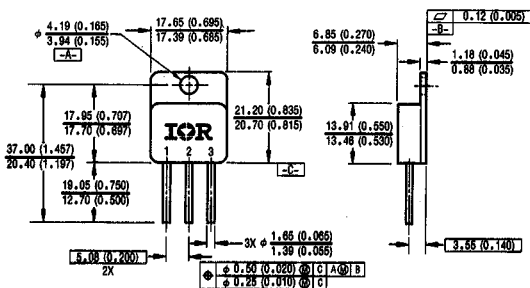
FEATURES:

- Repetitive Avalanche Rating
- Dynamic dv/dt Rating
- Isolated and Hermetically Sealed
- Alternative to TO-3 Package
- Simple Drive Requirements
- Ease of Paralleling
- Ceramic Eyelets

CASE STYLE AND DIMENSIONS



BERYLLIA WARNING PER MIL-S-19500
SEE PAGE I-470



NOTES

- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M - 1982.
2 ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

*For optional leadforms see page I-470, fig. 15

LEGEND

- LEGEND
- | | |
|---|--------|
| 1 | DRAIN |
| 2 | SOURCE |
| 3 | GATE |

Conforms to JEDEC Outline TO-258AA*
Dimensions in Millimeters and (Inches)

Absolute Maximum Ratings

Parameter	IRFV460	Units
I_D @ $V_{GS} = 0V$, $T_C = 25^\circ C$ Continuous Drain Current	21	A
I_D @ $V_{GS} = 0V$, $T_C = 100^\circ C$ Continuous Drain Current	13	
I_{DM} Pulsed Drain Current ①	84	
P_D @ $T_C = 25^\circ C$ Max. Power Dissipation	300	W
Linear Derating Factor	2.4	W/K ⑤
V_{GS} Gate-to-Source Voltage	± 20	V
E_{AS} Single Pulse Avalanche Energy ②	480	mJ
I_{AR} Avalanche Current ①	21	A
E_{AR} Repetitive Avalanche Energy ①	30	mJ
dv/dt Peak Diode Recovery dv/dt ③	3.5	V/ns
T_J Operating Junction Temperature	-55 to 150	$^\circ C$
T_{STG} Storage Temperature Range		
Lead Temperature	300 (0.063 in. (1.6 mm) from case for 10s)	
Weight	10.9 (typical)	g

Electrical Characteristics @ $T_J = 25^\circ C$ (Unless Otherwise Specified)

Parameter		Min.	Typ.	Max.	Units	Test Conditions		
BV_{DSS}	Drain-to-Source Breakdown Voltage	500	—	—	V	$V_{GS} = 0V$, $I_D = 1.0$ mA		
$\Delta BV_{DSS}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	0.63	—	V/°C	Reference to 25°C, $I_D = 1.0$ mA		
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance	—	—	0.27	Ω	$V_{GS} = 10V$, $I_D = 13A$ ④		
		—	—	0.31		$V_{GS} = 10V$, $I_D = 21A$		
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}$, $I_D = 250$ μA		
g_{fs}	Forward Transconductance	13	—	—	S (S)	$V_{DS} = 15V$, $I_{DS} = 13A$ ④		
I_{DSS}	Zero Gate Voltage Drain Current	—	—	25	μA	$V_{DS} = \text{Max. Rating}$, $V_{GS} = 0V$		
		—	—	250		$V_{DS} = 0.8 \times \text{Max. Rating}$ $V_{GS} = 0V$, $T_J = 125^\circ C$		
I_{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	$V_{GS} = 20V$		
I_{GSS}	Gate-to-Source Leakage Reverse	—	—	-100		$V_{GS} = -20V$		
Q_g	Total Gate Charge	—	—	190	nC	$V_{GS} = 10V$, $I_D = 21A$		
Q_{gs}	Gate-to-Source Charge	—	—	27		$V_{DS} = 0.5 \times \text{Max. Rating}$		
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	135		See Fig. 6 and 14		
$t_{d(on)}$	Turn-On Delay Time	—	—	35	ns	$V_{DD} = 250V$, $I_D = 21A$, $R_G = 2.350$		
t_r	Rise Time	—	—	120		See Fig. 11		
$t_{d(off)}$	Turn-Off Delay Time	—	—	130				
t_f	Fall Time	—	—	98				
L_D	Internal Drain Inductance	—	8.7	—	nH	Measured from the drain lead, 6 mm (0.25 in.) from package to center of die.	Modified MOSFET symbol showing the internal inductances. 	
L_S	Internal Source Inductance	—	8.7	—		Measured from the source lead, 6 mm (0.25 in.) from package to source bonding pad.		
C_{iss}	Input Capacitance	—	4300	—	pF	$V_{GS} = 0V$, $V_{DS} = 25V$		
C_{oss}	Output Capacitance	—	1000	—		$f = 1.0$ MHz		
C_{rss}	Reverse Transfer Capacitance	—	250	—		See Fig. 5		



Source-Drain Diode Ratings and Characteristics

Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S Continuous Source Current (Body Diode)	—	—	21	A	Modified MOSFET symbol showing the integral Reverse p-n junction rectifier. 
I_{SM} Pulsed Source Current (Body Diode) ①	—	—	84		
V_{SD} Diode Forward Voltage	—	—	1.8	V	$T_J = 25^\circ\text{C}$, $I_S = 21\text{A}$, $V_{GS} = 0\text{V}$ ④
t_{rr} Reverse Recovery Time	—	—	580	nS	$T_J = 25^\circ\text{C}$, $I_F = 21\text{A}$, $di/dt \leq 100\text{ A}/\mu\text{s}$ ④
Q_{RR} Reverse Recovery Charge	—	—	8.1	μC	$V_{DD} \leq 50\text{V}$
t_{on} Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

Thermal Resistance

Parameter	Min.	Typ.	Max.	Units	Test Conditions
R_{thJC} Junction-to-Case	—	—	0.42	K/W ⑤	
R_{thCS} Case-to-Sink	—	0.21	—		Mounting surface flat, smooth, and greased
R_{thJA} Junction-to-Ambient	—	—	30		Typical socket mount

① Repetitive Rating; Pulse width limited by maximum junction temperature (see figure 9)
Refer to current HEXFET reliability report

② @ $V_{DD} = 50\text{V}$, Starting $T_J = 25^\circ\text{C}$,
 $L \geq 2.0\text{ mH}$, $R_G = 25\Omega$,
Peak $I_L = 21\text{A}$

③ $I_{SD} \leq 21\text{A}$, $di/dt \leq 160\text{ A}/\mu\text{s}$,
 $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^\circ\text{C}$
Suggested $R_G = 2.35\Omega$

④ Pulse width $\leq 300\text{ }\mu\text{s}$; Duty Cycle $\leq 2\%$

⑤ K/W = $^\circ\text{C}/\text{W}$
W/K = $\text{W}/^\circ\text{C}$

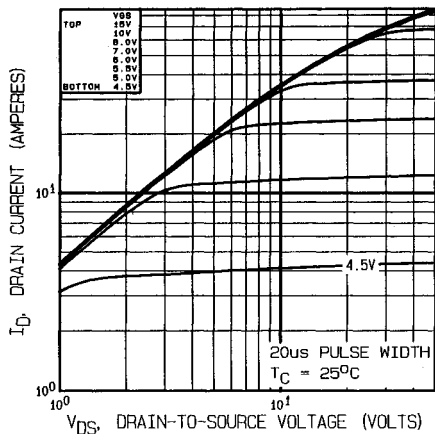
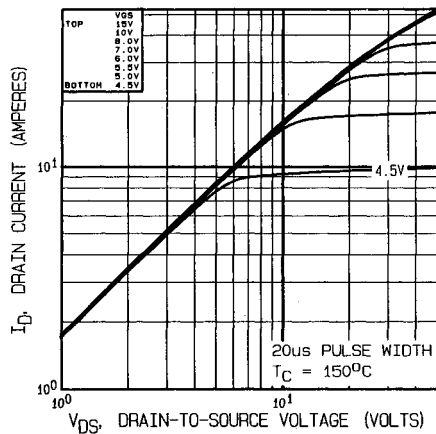
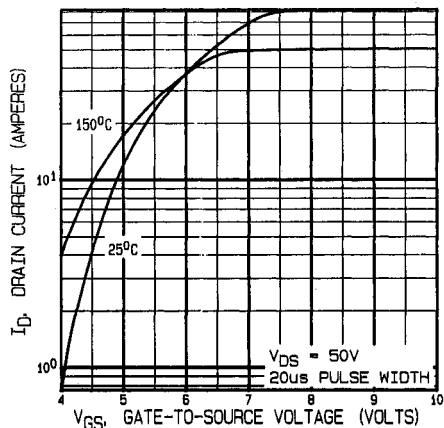
Fig. 1 — Typical Output Characteristics, $T_C = 25^\circ\text{C}$ Fig. 2 — Typical Output Characteristics, $T_C = 150^\circ\text{C}$ 

Fig. 3 — Typical Transfer Characteristics

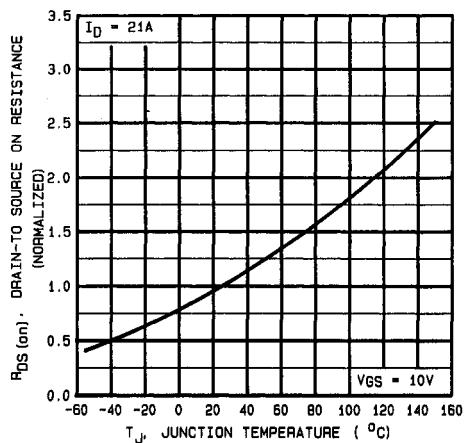
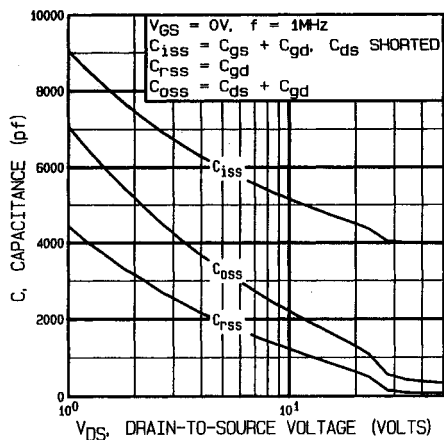
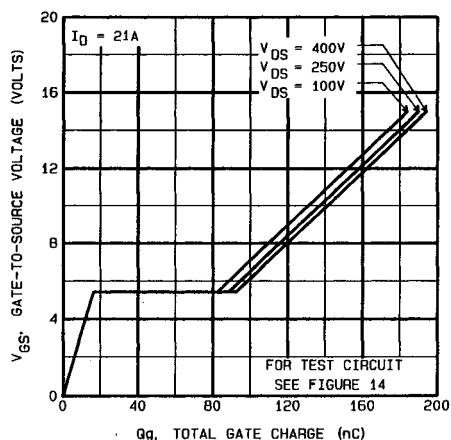
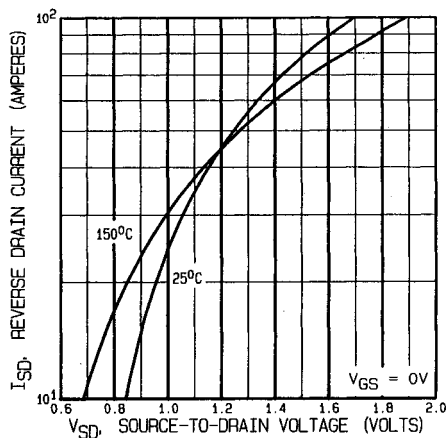
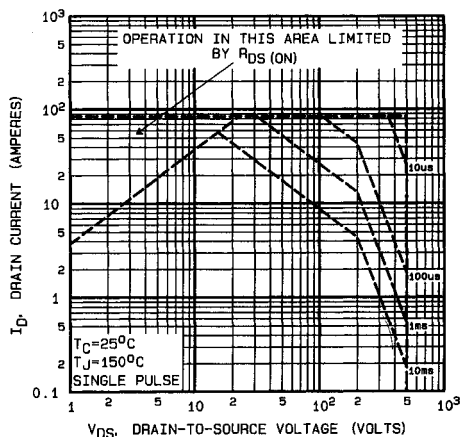


Fig. 4 — Normalized On-Resistance Vs. Temperature


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

Fig. 7 — Typical Source-Drain Diode Forward Voltage

Fig. 8 — Maximum Safe Operating Area

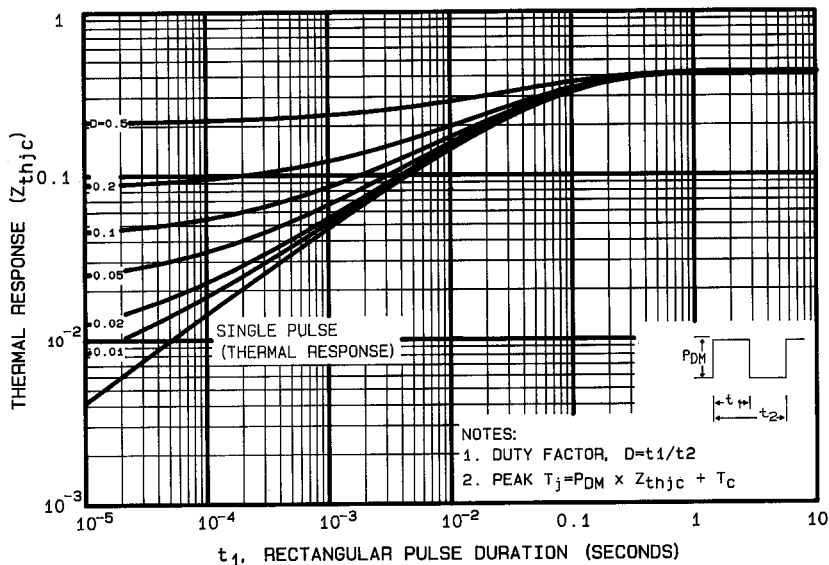


Fig. 9 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

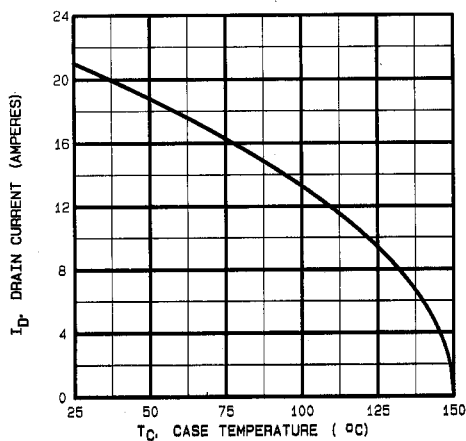


Fig. 10 — Maximum Drain Current Vs. Case Temperature

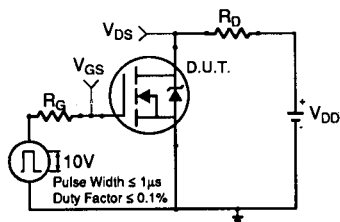


Fig. 11a — Switching Time Test Circuit

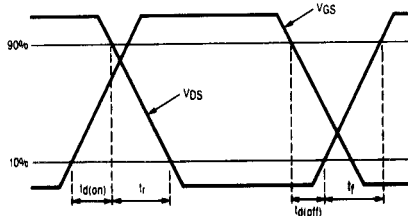
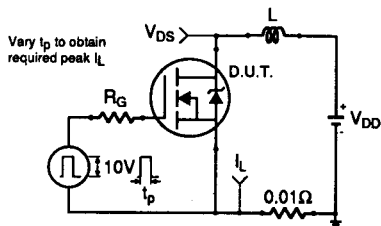
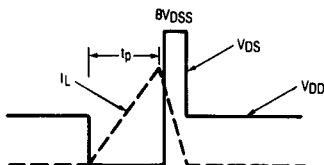
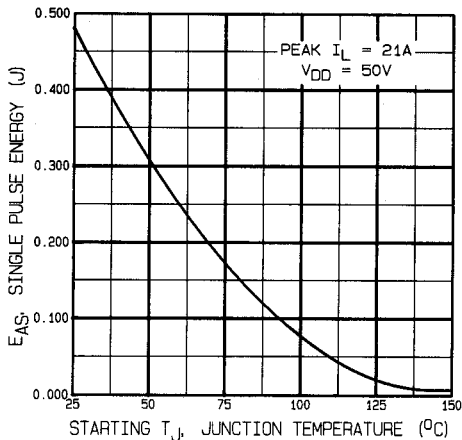
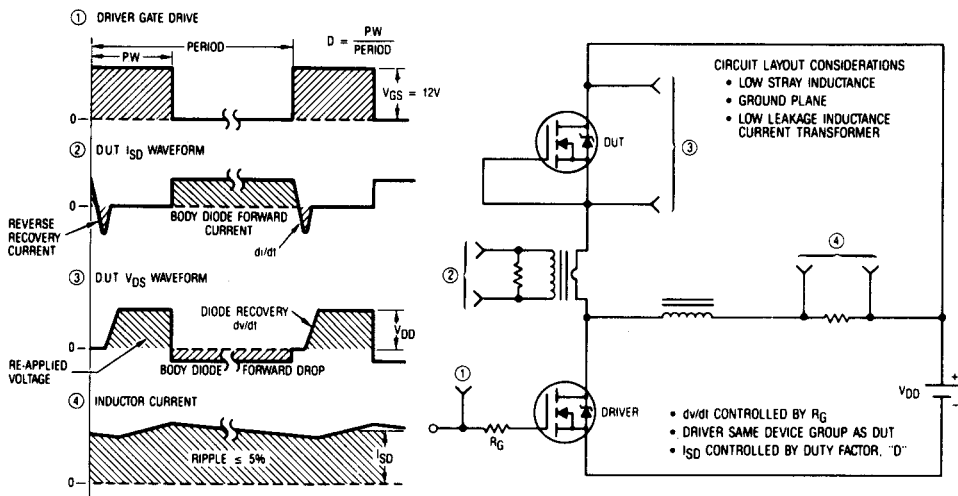


Fig. 11b — Switching Time Waveforms


Fig. 12a — Unclamped Inductive Test Circuit

Fig. 12b — Unclamped Inductive Waveforms

Fig. 12c — Maximum Avalanche Energy Vs. Starting Junction Temperature

Fig. 13 — Peak Diode Recovery dv/dt Test Circuit

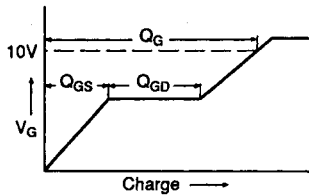


Fig. 14a — Basic Gate Charge Waveform

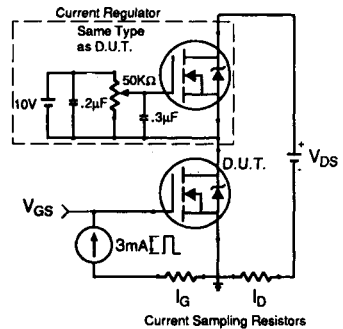


Fig. 14b — Gate Charge Test Circuit

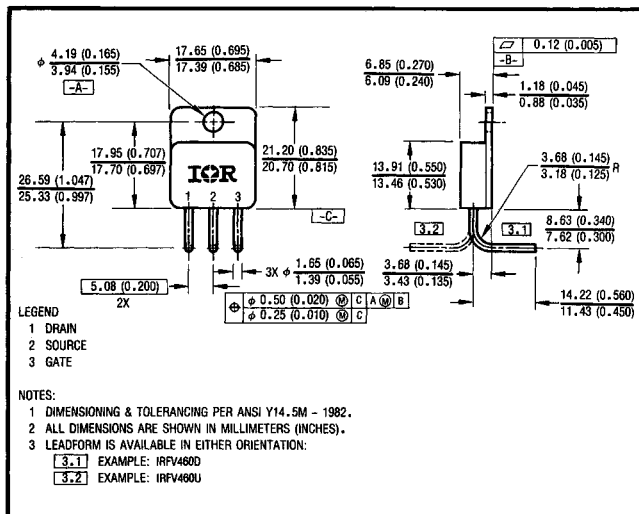


Fig. 15 — Optional Leadforms for Outline TO-258

BERYLLIA WARNING PER MIL-3-19500

Packages containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.



IRFY Series Data Sheet

The IRFY Data Sheet describes 12 devices, 8 N-Channel and 4 P-Channel, all contained in the TO-257AB package. This data sheet is arranged to show common tabular and graphical information between devices.

Absolute maximum ratings and parametric data are presented in tabular format with devices grouped according to generically shared parameters. For each parametric rating, devices are categorized by N and P channel and listed in alpha-numeric order. The conditions specified for a given parametric test are provided in the right hand column of each table.

Graphical information is grouped by devices in

alphabetical order. Where the information is device specific, we have assigned a numeric character for the graph type and an alpha character to a given device. (See Table A below). Where graphs are polarity specific as in figures 10, 12, 14 and 15, we have indicated N-Channel or P-Channel. The Thermal Impedance Graph (Fig. 11) is the only exception where a graph is common to both N-Channel and P-Channel devices since the thermal impedance is only dependent on the die size and package.

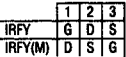
In Table A below, a legend is provided cross referencing the part number to its assigned alpha code. A given device will retain this alpha code for each device specific graph.

Table A

DEVICE	ALPHA DESIGNATION
IRFY044	a
IRFY120	b
IRFY130	c
IRFY140	d
IRFY240	e
IRFY340	f
IRFY430	g
IRFY440	h
IRFY9120	i
IRFY9130	j
IRFY9140	k
IRFY9240	l

HEXFET, CECC Qualified — Europe

TO257/HEXFET/N-Channel

Basic Type	V _{DS} (V)	R _{DS(on)} (Ohms)	CECC Specification	Issue No.	Issue Date	Level of Quality Assessment and CECC 50 000 Screen Level Options	Case Outline
IRFY044(M)	60	0.03	50 012-062	1	10/91	E, EA, EB, EC, ED	TO-257AA Y-PAK 
IRFY120(M)	100	0.31	50 012-060			E, EA, EB, EC, ED	
IRFY130(M)	100	0.19	50 012-061			E, EA, EB, EC, ED	
IRFY140(M)	100	0.092	50 012-062			E, EA, EB, EC, ED	
IRFY240(M)	200	0.19	50 012-062			E, EA, EB, EC, ED	
IRFY340(M)	400	0.55	50 012-062			E, EA, EB, EC, ED	
IRFY430(M)	500	1.50	50 012-061			E, EA, EB, EC, ED	
IRFY440(M)	500	0.85	50 012-062			E, EA, EB, EC, ED	
TO257/HEXFET/P-Channel							
IRFY9120(M)	-100	0.60	50 012-063	1	10/91	E, EA, EB, EC, ED	
IRFY9130(M)	-100	0.31	50 012-064			E, EA, EB, EC, ED	
IRFY9140(M)	-100	0.21	50 012-065			E, EA, EB, EC, ED	
IRFY9240(M)	-200	0.50	50 012-065			E, EA, EB, EC, ED	

FOR OTHER GOVERNMENT/SPACE QUALIFIED PRODUCTS SEE SECTION E.